

/ Descriptions

Dual P-Channel MOSFET in a SOT23-6 Plastic Package.

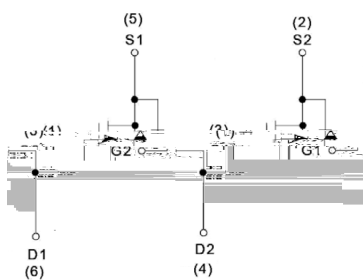
/ Features

Super high dense cell design for low $R_{DS(ON)}$, Rugged and reliable. HF product.

/ Applications

Power Management in Notebook computer, Portable Equipment and Battery powered systems.

/ Equivalent Circuit



/ Pinning



PIN1 G1 PIN 2 S2 PIN 3 G2

PIN 4 D2 PIN 5 S1 PIN 6 D1

/ Marking

See Marking Instructions

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	-20	V
Gate-Source Voltage	V_{GSS}	± 12	V
Continuous Drain Current	I_D^*	-3.0	A
Pulsed Drain Current	I_{DM}^*	-12	A
Diode Continuous Forward Current	I_S^*	-2.0	A
Power Dissipation for Single Operation	$P_D^* (T_a=25^\circ\text{C})$	1.25	W
Power Dissipation for Single Operation	$P_D^* (T_a=100^\circ\text{C})$	0.5	W
Maximum Junction Temperature	T_j	150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 150	$^\circ\text{C}$
Thermal Resistance-Junction to Ambient	R_{JA}^*	70	$^\circ\text{C/W}$

Note:

* Surface Mounted on 1in2 pad area, $t \leq 10\text{sec.}$

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V \quad I$				

/ Electrical Characteristics(Ta=25 °C)

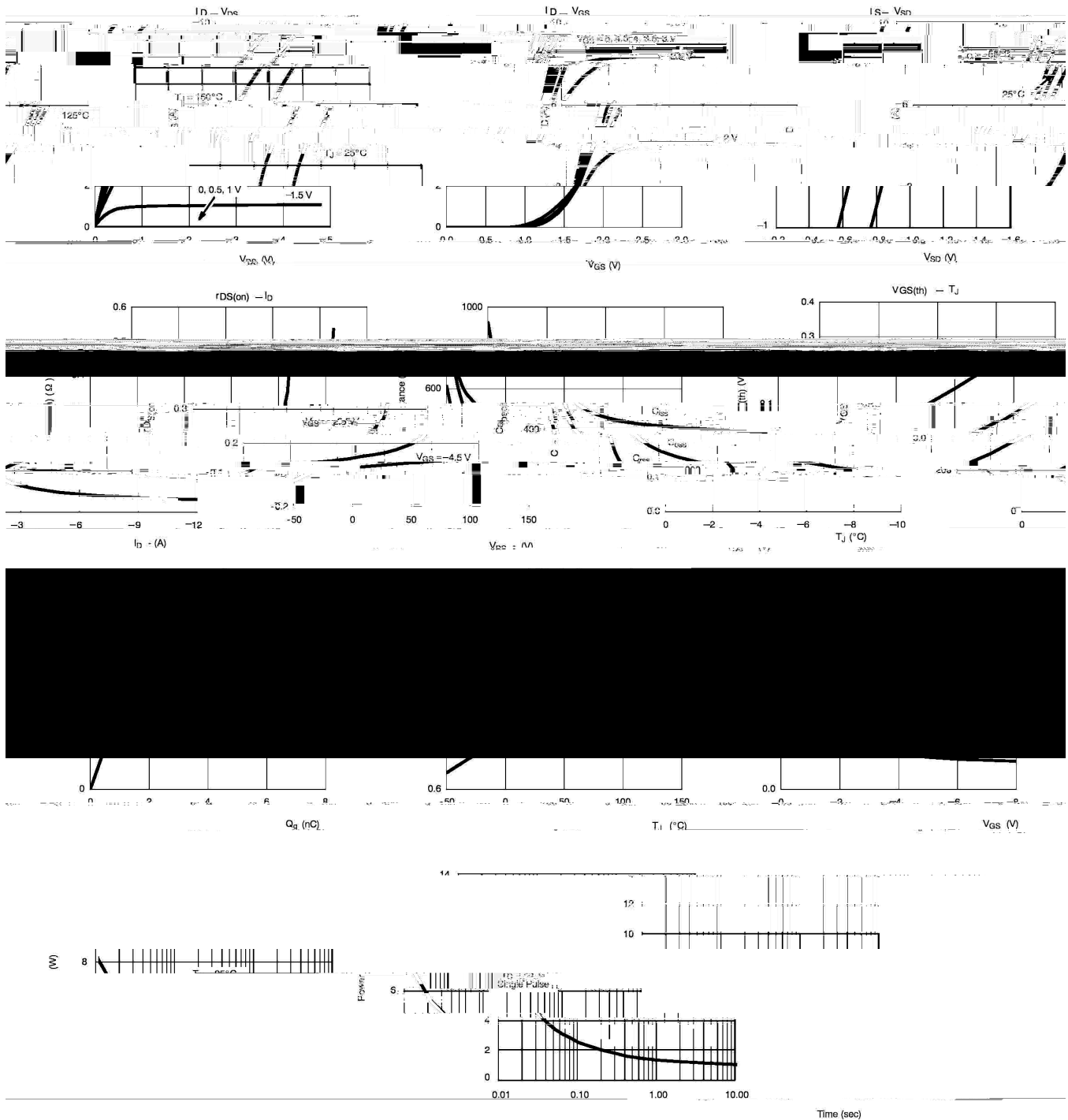
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Gate Resistance	R_G^b	$V_{GS}=0V$ $V_{DS}=0V$ $F=1MHz$		6		
Input Capacitance	C_{iss}^b	$V_{GS}=0V$ $V_{DS}=-6V$ Frequency=1.0MHz		415		pF
Output Capacitance	C_{oss}^b			223		
Reverse Transfer Capacitance	C_{rss}^b			84		
Turn-on Delay Time	$t_{d(ON)}^b$	$V_{DD}=-6V$ $R_L=6$ $I_{DS}=-1A$ $V_{GEN}=-10V$ $R_G=6$		13	25	ns
Turn-on Rise Time	T_r^b			36	60	
Turn-off Delay Time	$T_{d(OFF)}^b$			42	70	
Turn-off Fall Time	T_f^b			34	60	

Notes:

a : Pulse test ; pulse width 300 μ s, duty cycle 2%.

b : Guaranteed by design, not subject to production testing.

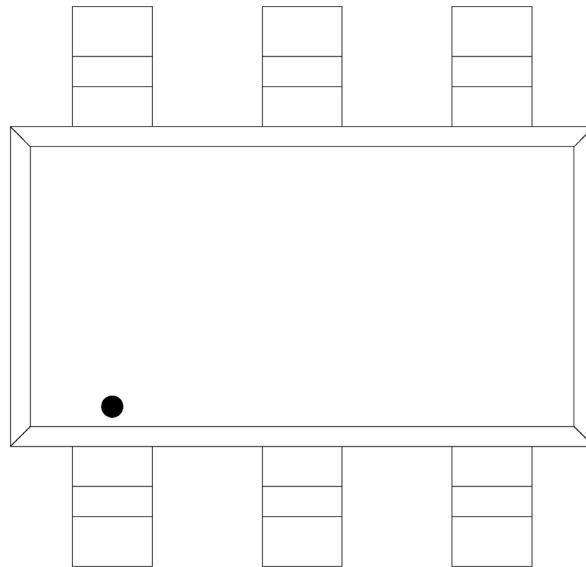
/ Electrical Characteristic Curve



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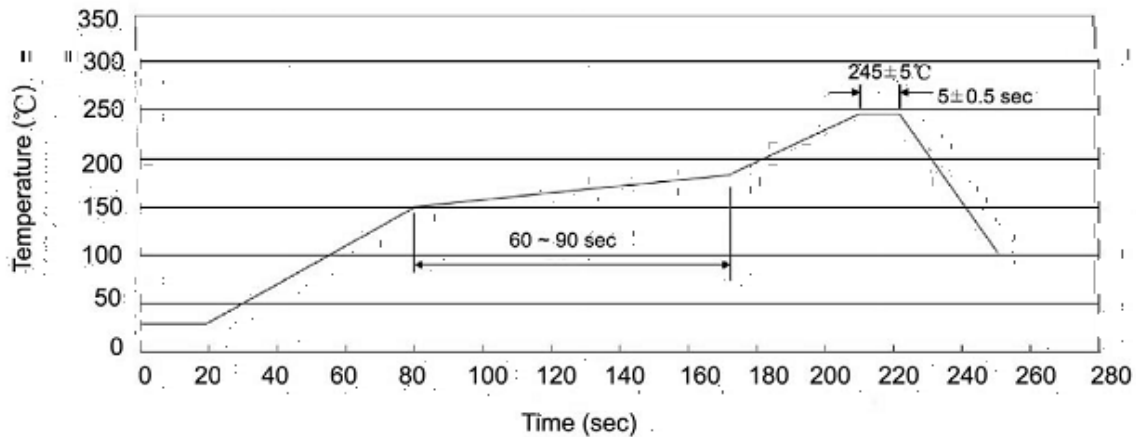
Rev.C May.-2019

/ Marking Instructions



4953D

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-----|-----|----|---------|---|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245 | 5 | 5 | 0.5sec; | 2.Peak Temp.:245 5 , Duration:5 0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp.:260±5℃ Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱